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ABSTRACT OF THE DISCLOSURE (FIG. 1)

COATING METHOD AND APPARATUS

A coating apparatus has a nozzle for delivering a photo-resist liquid onto a semiconductor wafer supported by a spin chuck. The nozzle is movable between a supply position and a wait position. At the wait position, there are a roller which is rotatable in one direction and has a circumferential surface with thinner thereon, and a wiper for wiping the circumferential surface of the roller. While the nozzle is located at the wait position, a waiting mode is first performed, and a preparing mode is then performed immediately before the nozzle is moved from the wait position to the supply position. In the waiting mode, delivery of the photo-resist liquid from the nozzle is stopped and the wiper is located at a retreat position, such that a tip port of the nozzle is wetted by the thinner present on the circumferential surface of the roller. In the preparing mode, the processing liquid is delivered from the tip port of the nozzle onto the circumferential surface of the roller, and the wiper is located at a project position such that the processing liquid is removed from the circumferential surface of the roller.